

Connector for SD Memory Card

SCDA Series



Compact low-profile type with a width of 27mm features high reliability contact structure.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



Features

- Media half-lock structure stops media from flying out during ejection, preventing the dropping and loss of media.
- Media detection switch adopts a highly reliable structure where the contact slides at ON/OFF to ensure detection of media insertion timing.
- Also compatible to MultiMediaCard™.
- Compact size and low-profile.

Applications

- For digital still cameras, digital camcorders, mobile phones, PCs and personal digital assistants
- For home audio equipment (TVs, set top boxes, etc.)
- For stereo systems
- For portable memory players

Typical Specifications

Items		Specifications	
Structure	Applicable media	SD Memory Card/MultiMediaCard™	
	Mounting type	Surface mounting type	
	Mounting style	Standard mount/Reverse mount	
	Media ejection structure	Push-push type/Manual insertion/removal	
Performance	Operating temperature range	-25°C to +60°C	
	Voltage proof	100V AC 1minute/500V AC 1minute (SCDA3)	
	Insulation resistance (Initial)	1,000MΩ min.	
	Contact resistance (Initial)	Connector contacts	100mΩ max.
		Detection switch	500mΩ max.
Insertion and removal cycle	10,000cycles		

Product Line

Media ejection structure	Mounting style	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.	
Push-push type	Standard mount	Inner tail without frame legs	0	Taping	SCDA3A0102	1	
		Inner tail with frame legs			SCDA3A0202	2	
		Slim type With boss			SCDA4A0200	3	
		Slim type Without boss			SCDA4A0301	4	
		Card eject stroke 8mm			SCDA7A0101	5	
	Reverse mount	Slim type		1.5	Tray	SCDA7A0200	6
				1.8		SCDA4A0400	7
						SCDA5A0201	8
						SCDA6A0101	9
Manual insertion and removal type	Standard mount	Header type	0	Taping	SCDA3C0102	10	

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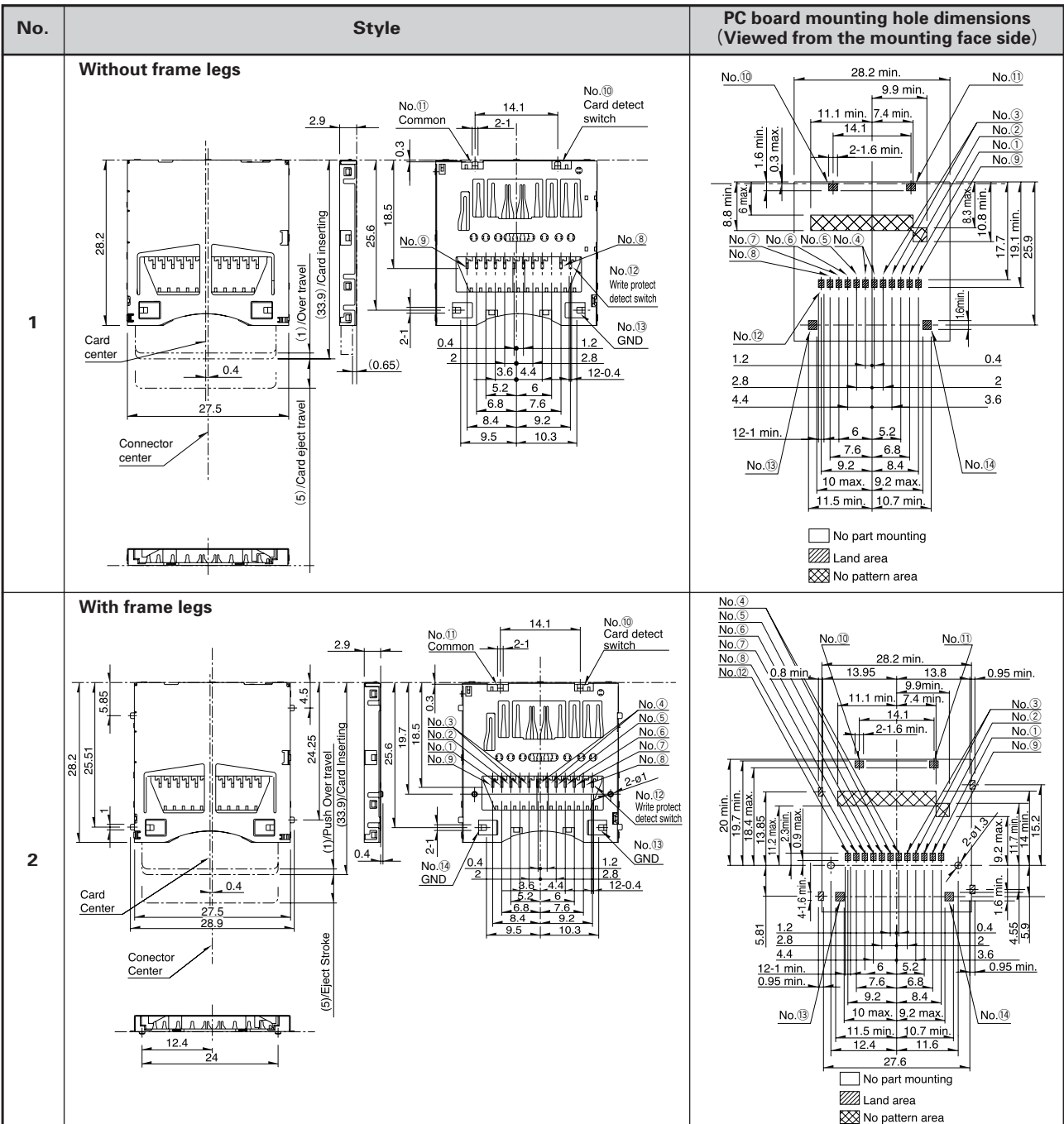
For Express Card™

For CMOS Camera Module

Dimensions

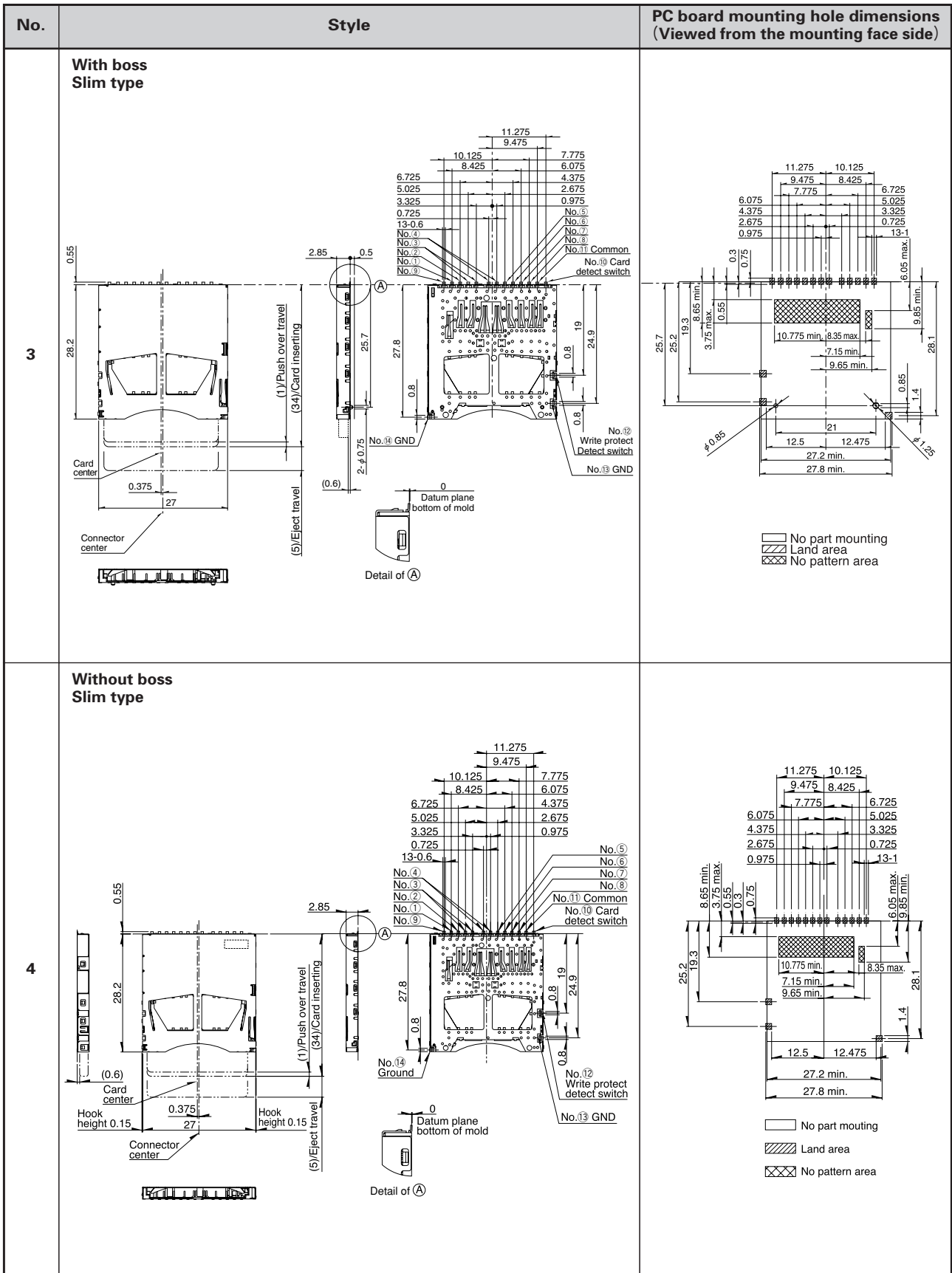
Standard mount (Inner tail)

Unit:mm



Dimensions Standard mount

Unit:mm



Dimensions
Standard mount

Unit:mm

No.	Style	PC board mounting hole dimensions (Viewed from the mounting face side)
5	<p>Stand-off 0mm Card eject stroke 8mm</p> <p>Connector center Card center Center line of card</p>	<p>Land area No part area</p>
6	<p>Stand-off 1.5mm Card eject stroke 8mm</p> <p>Card center Connector center Center line of card</p>	<p>Land area No part area</p>

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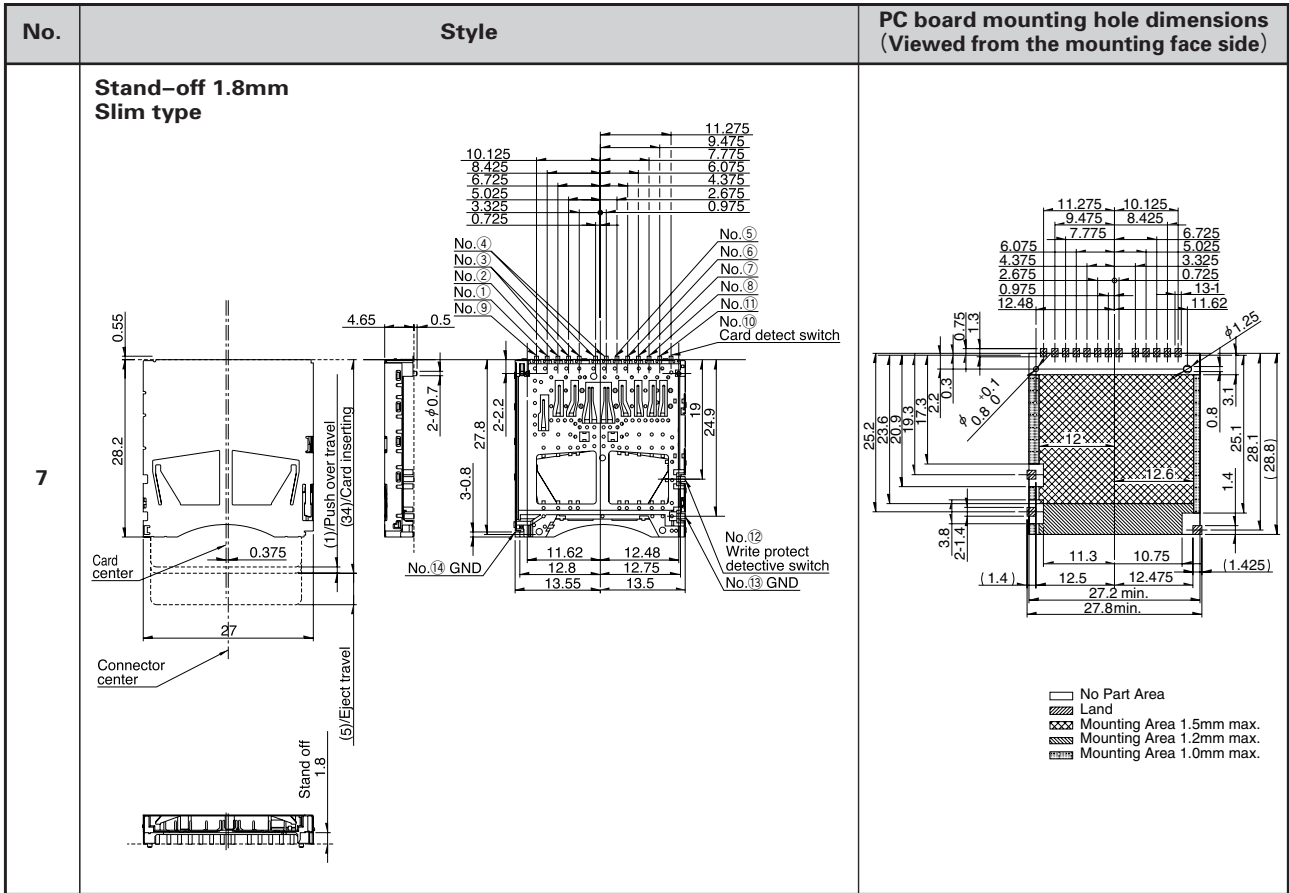
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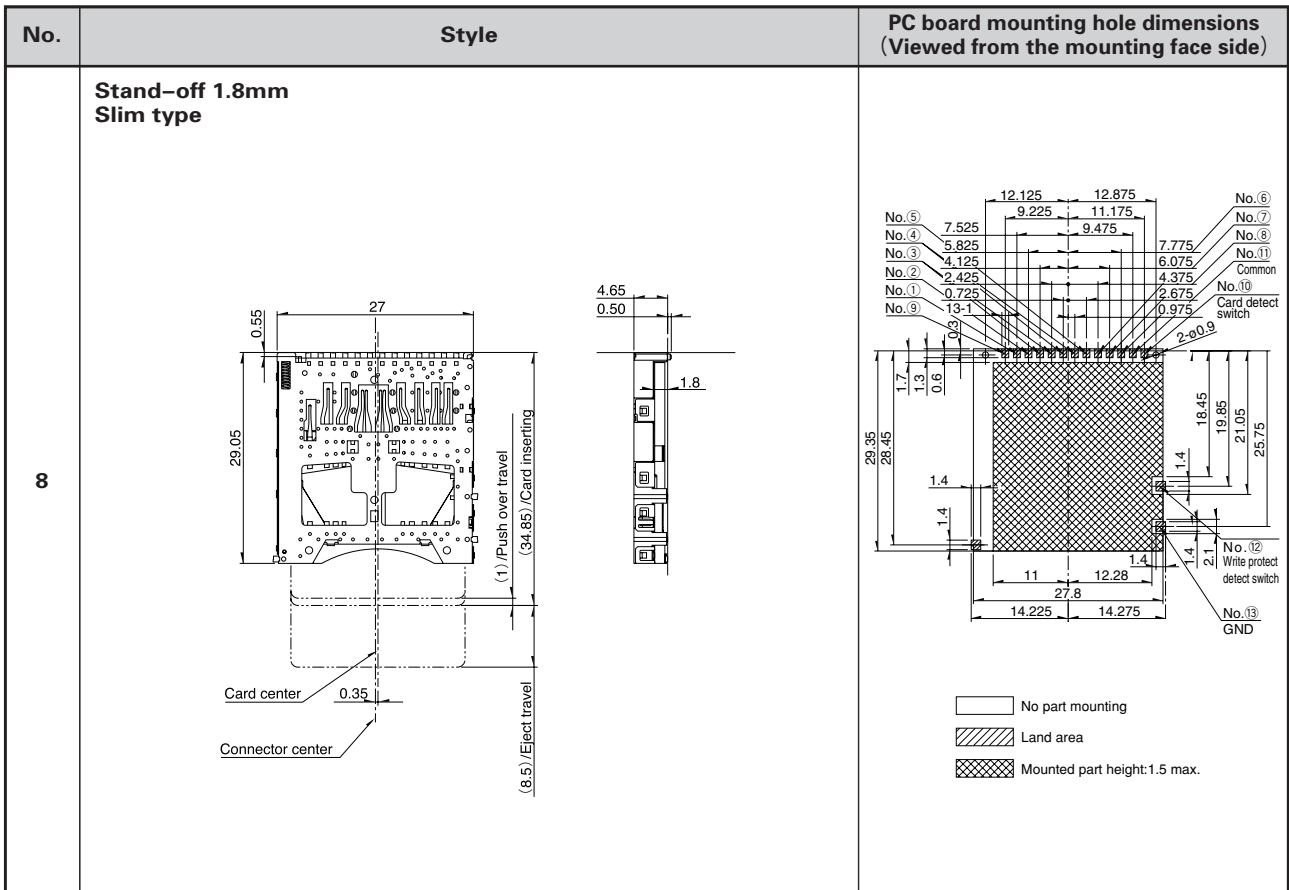
Dimensions
Standard mount

Unit:mm



Dimensions
Reverse mount

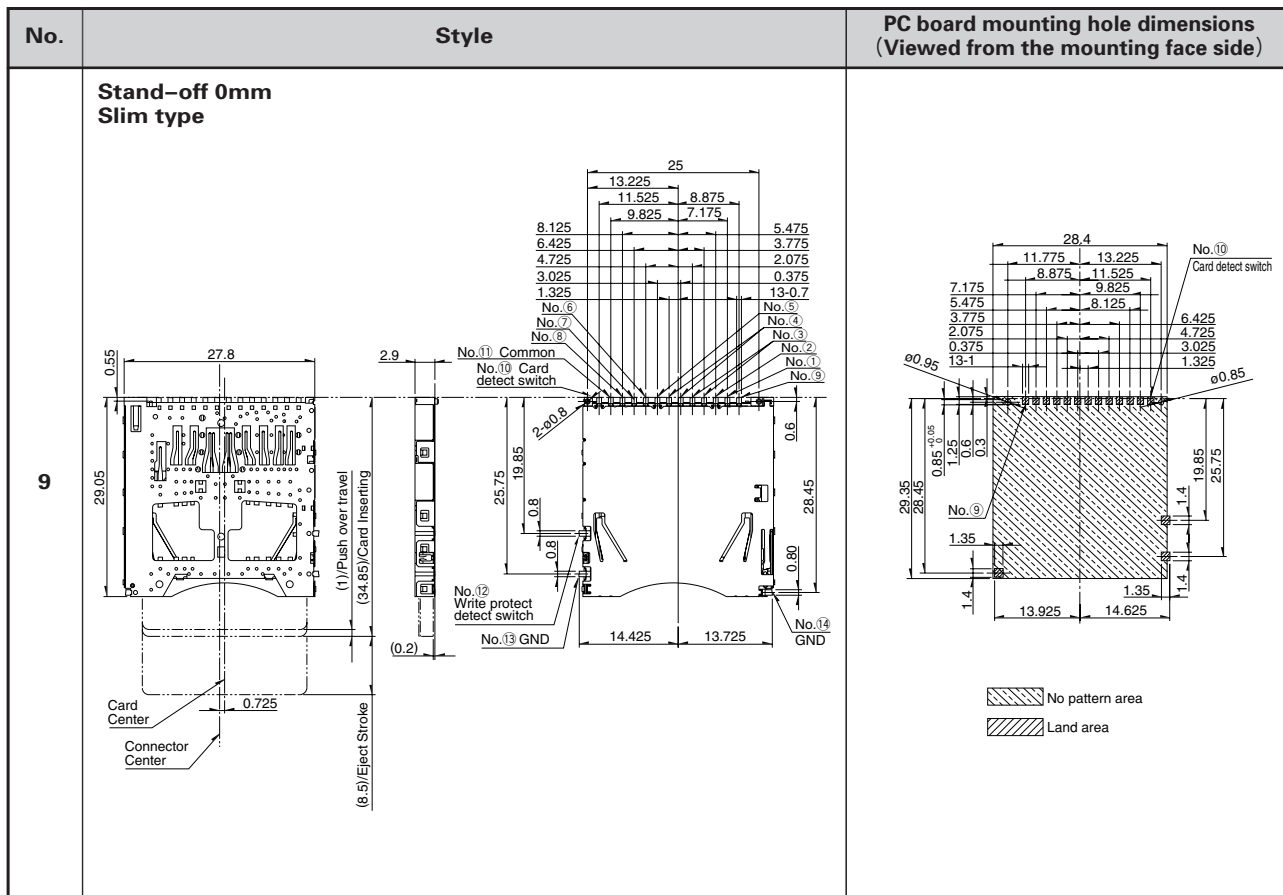
Unit:mm



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Dimensions
Reverse mount

Unit:mm



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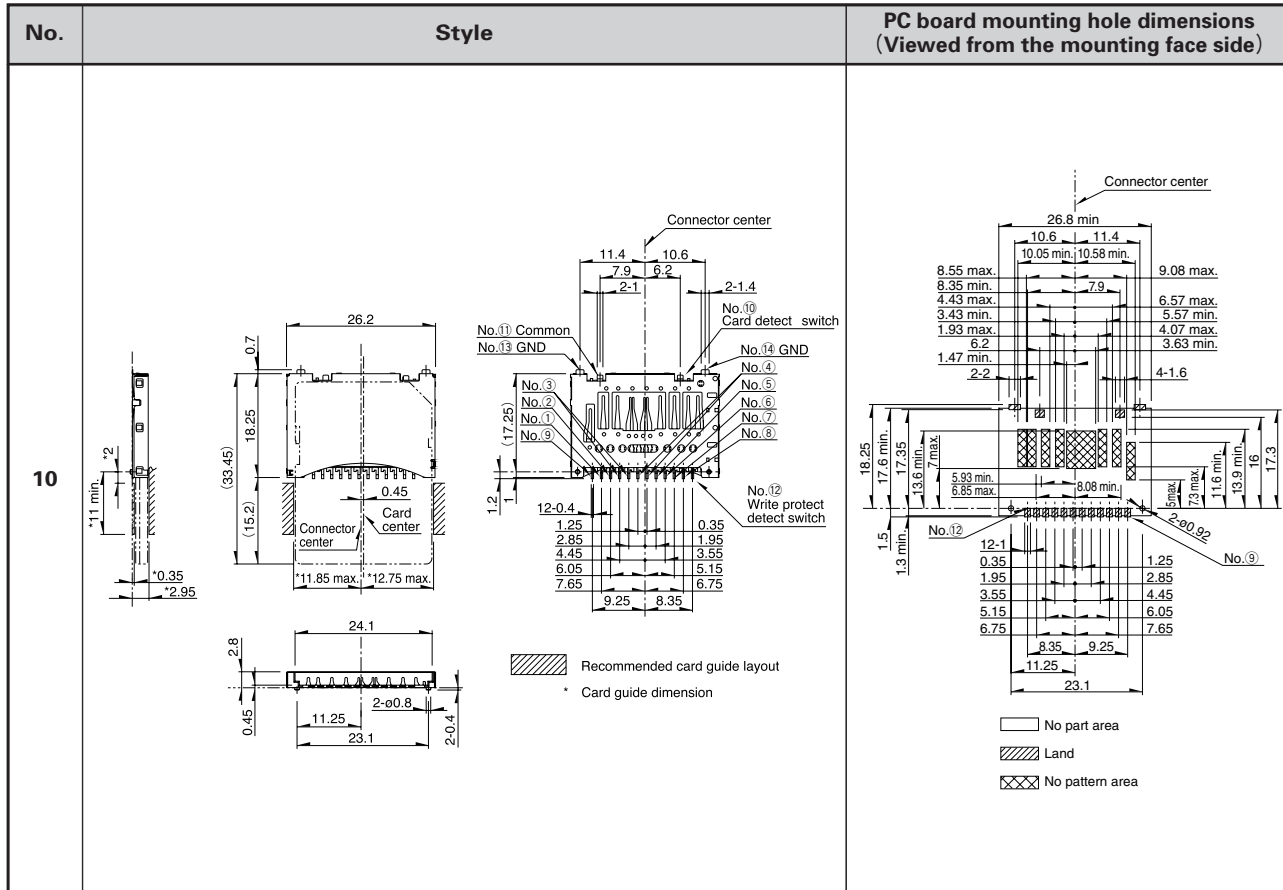
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Dimensions
Header type

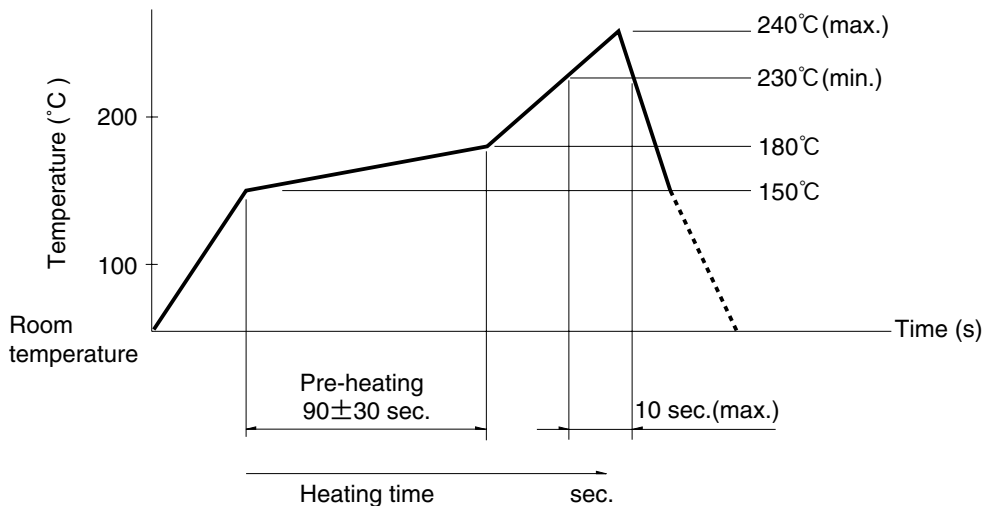
Unit:mm



Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions for using this product

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. Avoid use of water-soluble soldering flux, since it may corrode the product.
3. Check and conform to reflow soldering requirements under actual mass production conditions.
4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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